



Material Composition Declaration

EPC2019

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	4.6 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	4.1309	89.17	91.74	891727
	Silicon oxide	7631-86-9	0.0160	0.35		3452
	Silicon nitride	12033-89-5	0.0051	0.11		1093
	Gallium nitride	25617-97-4	0.0300	0.65		6479
	Aluminum	7429-90-5	0.0306	0.66		6605
	Aluminum nitride	24304-00-5	0.0074	0.16		1591
	Titanium	7440-32-6	0.0006	0.01		127
	Titanium nitride	25583-20-4	0.0026	0.06		559
	Copper	7440-50-8	0.0010	0.02		220
	Tungsten	7440-33-7	0.0006	0.01		127
	Polyimide		0.0251	0.54		5411
Under Bump Metal	Titanium	7440-32-6	0.0006	0.01	1.12	133
	Nickel	7440-02-0	0.0182	0.39		3929
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0330	0.71		7114
Solder Bump	Tin	7440-31-5	0.3227	6.96	7.14	69649
	Silver	7440-22-4	0.0083	0.18		1786
	Copper	7440-50-8	0.0000	0.00		0
Sum in total:			4.6	100.00	100	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.